ound SMD Power Inductor
MWPH6045S Series
· U
635mg/pcs Typ.
tronics Co., Ltd.

Comments:

	Version Change History						
Rev.	Date	ltem	Changed Contents	Change Reasons	Drawing	Check	Approval
01	1	/	New release	1	Jingkui Li	Pengfei Cheng	Yubo Su

Automotive

Na	lite me	P -
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	Automotive	

- 1 Scope
 - 1.1 Scope of parts

This specification applies to the AMWPH6045S Series of wire wound SMD power inductor for automotive electronics based on AEC-Q200D.

1.2 Scope of application

Product numbers recorded in this specification are used for automotive applications.

1.3 Operating and storage temperature

The part temperature (ambient + temp. rise) should not exceed 125°C under worst case operating conditions. Circuit design, component placement, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature

should be verified in the end application.

- 1) Operating and storage temperature range (individual chip without packing):-40°C ~+125°C (including self-heating)..
- 2) Storage temperature range (packaging conditions): -10°C~+40°C and RH 70% (Max.)
- 3) MSL: Level 1

2 Product Description and Identification (Part Number)

1) Description:

AMWPH6045S Series of Wire wound SMD power inductor.

2) Product Identification (Part Number)

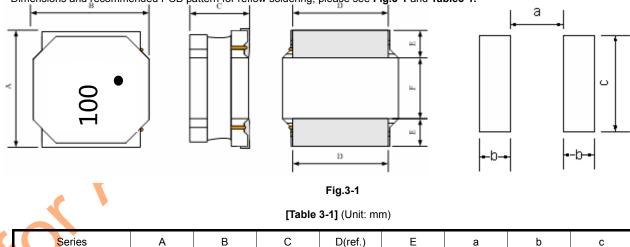
А	MWPH	6045	S	1R0	М	Т	Y01
1	2	3	4	5	6	7	8

①Feature Code	A: for Automotive		
2 Product Type	MWPH: Wire wound SMD power inductor		
③External Dimensions(L×W×H) [mm]	6045: 6.0×6.0×4.4		
④Feature type	S:Standard Type		
5Nominal Inductance	1R0=1.0uH,100=10uH,101=100uH		
©Inductance Tolerance	M: ±20%,N: ±30%		
⑦Packing Code	T: Tape Carrier Package		
8 Special Process code	Standard product is blank		

3 Shape and Dimensions

AMWPH6045S

Dimensions and recommended PCB pattern for reflow soldering, please see Fig.3-1 and Table3-1.



4.9±0.3

1.55±0.3

2.5 Typ.

2.2 Тур.

5.7Typ.

 $4.4\!\pm\!0.2$

Note: ※ 1Ddimension: Measure the total length of both ends of the electrode.

6.0±0.3

6.0±0.3

4

Customer P/N	Part Number	Inductance	Min. Self-resonant	DC Res	sistance	Satur Curr		Heat I Cur	Rating rent	
		0.1MHz/1V	frequency	Max.	Тур.	Max.	Тур.	Max.	Тур.	Marking
	Units	μH	MHz	Ω	Ω	А	А	Α	А	
	Symbol	L	SRF	DC	CR	ls	at	Irr	ns	-
	AMWPH6045SR55MT	0.55±20%	137	0.009	0.007	13.50	15.50	5.90	6.50	R55
	AMWPH6045S1R0MT	1.0±20%	90	0.013	0.010	9.30	10.50	5.40	5.90	1R0
	AMWPH6045S1R5MT	1.5±20%	63	0.016	0.012	7.80	8.70	4.95	5.40	1R5
	AMWPH6045S2R2MT	2.2±20%	47	0.020	0.016	6.30	6.90	4.30	4.70	2R2
	AMWPH6045S4R7MT	4.7±20%	27	0.040	0.030	4.60	5.15	3.10	3.40	4R7
	AMWPH6045S6R3MT	6.3±20%	20	0.045	0.036	3.40	3.80	2.60	3.05	6R3
	AMWPH6045S100MT	10±20%	16	0.060	0.049	3.00	3.45	2.45	2.70	100
	AMWPH6045S150MT	15±20%	12	0.085	0.071	2.40	2.70	1.90	2.05	150
	AMWPH6045S220MT	22±20%	11	0.140	0.116	2.00	2.25	1.55	1.75	220
	AMWPH6045S330MT	33±20%	10	0.174	0.145	1.50	1.70	1.45	1.55	330
	AMWPH6045S470MT	47±20%	7.5	0.300	0.225	1.35	1.50	1.10	1.20	470
	AMWPH6045S680MT	68±20%	6.0	0.395	0.328	1.15	1.30	0.90	1.00	680
	AMWPH6045S101MT	100±20%	5.0	0.560	0.460	0.90	1.05	0.75	0.85	101
	AMWPH6045S121MT	120±20%	4.6	0.593	0.494	0.85	0.95	0.70	0.85	121

Electrical Characteristics

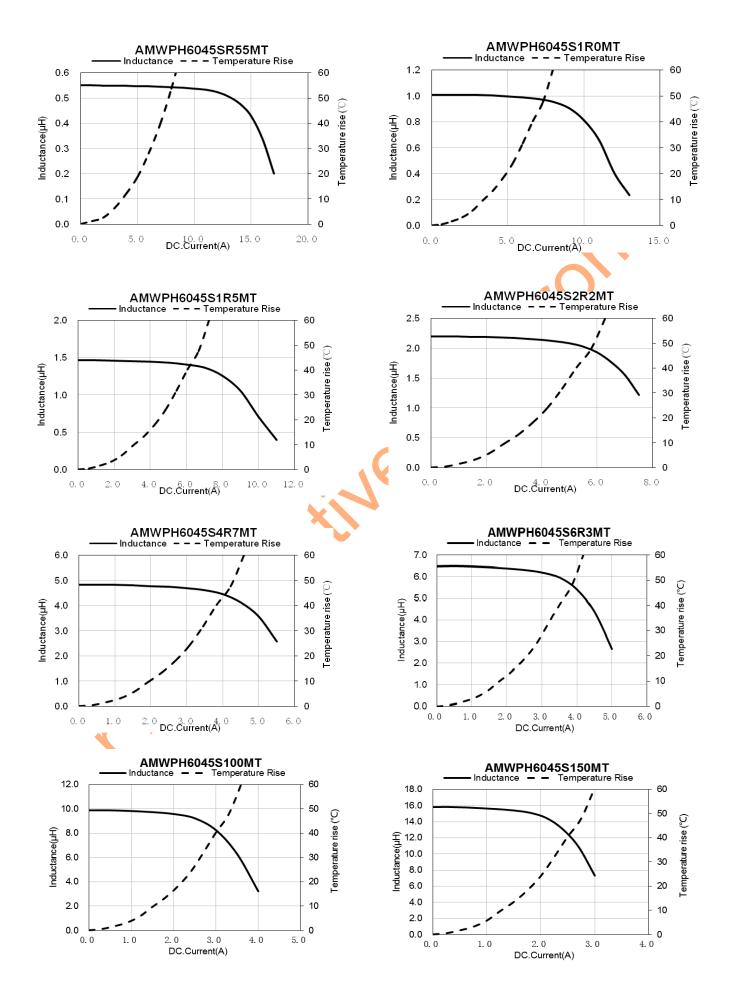
Note: ※ 1: Rated current: Isat (max.) or Irms (max.), whichever is smaller;

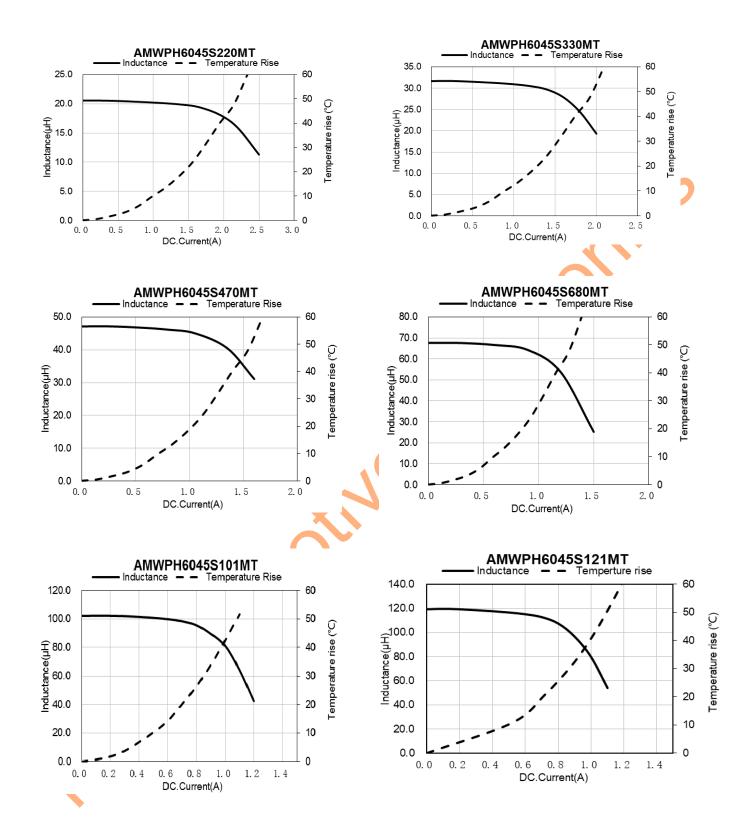
* 2: Saturation Current: Max. Value, DC current at which the inductance drops less than 30% from its value without current;

Typ. Value, DC current at which the inductance drops approximate 30% from its value without current;

- \times 3: Irms: DC current that causes the temperature rise (Δ T) from 20°C ambient. .ise .uue, ΔT is a
 - For Max. Value, $\Delta T < 40^{\circ}$ C; For Typ. Value, ΔT is approximate 40° C.

Appendix : Typical Electrical Characteristics





5 Test and Measurement Procedures

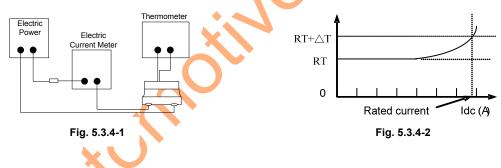
5.1 Test Conditions

5.1.1 Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

- a. Ambient Temperature: 20±15°C
- b. Relative Humidity: 65±20%
- c. Air Pressure: 86kPa to 106kPa
- 5.1.2 If any doubt on the results, measurements/tests should be made within the following limits:
 - a. Ambient Temperature: 20±2°C
 - b. Relative Humidity: 65±5%
 - c. Air Pressure: 86kPa to 106kPa

5.2 Visual Examination

- Inspection Equipment: Visual.
- 5.3 Electrical Test
 - 5.3.1 Inductance (L)
 - a. Refer to Item 4.Test equipment: WK3260B LCR meter or equivalent.
 - b. Test Frequency and Voltage: refers to Item 4.
 - 5.3.2 Direct Current Resistance (DCR)
 - a. Refer to Item 4.
 - b. Test equipment: HIOKI 3540 or equivalent.
 - 5.3.3 Saturation Current (Isat)
 - a. Refer to Item 4.
 - b. Test equipment: WK3260B LCR meter or equivalent.
 - 5.3.4 Temperature rise current (Irms)
 - a. Refer to Item 4.
 - b. Test equipment (see Fig. 5.3.4-1, Fig. 5.3.4-2): Electric Power, Electric current meter, Thermometer.
 - c. Measurement method
 - 1. Set test current to be 0 mA.
 - 2. Measure initial temperature of choke surface.
 - 3. Gradually increase current and measure choke temperature for corresponding current.
 - 4. Definition of Temperature rise current: DC current that causes the temperature rise (ΔT) from ambient temperature.



- 5.3.5Self-resonant frequency(SRF)
 - a. Refer to Item 4.

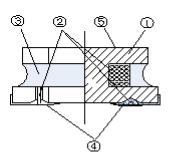
b.Test equipment: Agilent E4991A+16197or equivalent

5.4 Schematic Diagram



6 Structure

The structure of AMWPH6045S product, please refer to Fig.6-1 and Table 6-1. 1)



		[Table 6-1]
No.	Components	Material
1	Ferrite Core	NiZn Ferrite
2	Wire	Polyurethane system enameled copper wire
3	Magnetic Glue	Epoxy resin and magnetic powder
(4)	Electrodes	Ag/Ni/Sn+ Cu +Sn Alloy
5	Marking	Laser Marking

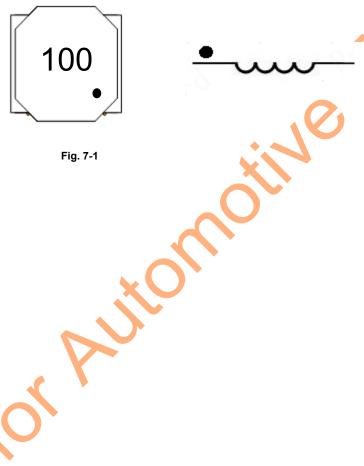
7 **Product Marking**

Please refer to Fig. 7-1.

Marking method: laser

o: polarity pointd

100: Inductance, refer to specifications

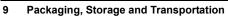


8 Re	Reliability Test				
No.	Test Items	Test Methods	Requirements		
1	Pre-and Post -Stress Electrical Test	Inductance of the components DC resistance of the components	 (1)The electrical values before the test meet the specifications (2)The electrical values after the test meet the rate of change requirements; Inductance change: Within ±10% 		
2	External Visual	Appearance of the components	(1)No visible mechanical damage		
3	Physical Dimension	Dimensions of the components	(1) meet the specifications		
4	Electrical Characterization	Ambient temperature 25°C(15+3min) → ambient temperature -40°C(15+3min) → ambient temperature +125°C(15+3min).	(1)Inductance change should be within ±10% of reference value measuring at 25℃		
5	Flammability	Refer to MIL-STD-202 Method 111、UL-94	 t1 or t2:≤10s; t1 plus t2 for the 5 specimens:≤50s; t2+t3 for each specimen:≤30s; No after-flame or after-glow of any specimen up to the holding clamp; No cotton indicator ignited by flaming particles or drops. 		
6	Terminal Strength	1.Precondition: 3 reflow cycles; 2.Test condition:17.7N,X,Ydirect, 60(+5)s,Speed:1.0mm/s.	(1)No visible mechanical damage		
7	Board Flex	1.Precondition: 3 reflow cycles; 2.Test condition: 2mm,60(+ 5)s.	(1)No visible mechanical damage		
8	Solder ability	Method 1: (1) pretreatment; 155°C, 4h (2) 235°C,5(-0,5,+0)s, 25 \pm 6 mm/s; (3) Solder: Sn/3.0Ag/0.5Cu Method 2: (1) Steam aging:8h \pm 15min; (2) 235°C,5(-0.5,+0)s, 25 \pm 6 mm/s; (3) Solder: Sn/3.0Ag/0.5Cu Method 3: (1) Steam aging:8h \pm 15min; (2) 260°C,7(-0.5,+0.5)s, 25 \pm 6 mm/s; (3) Solder: Sn/3.0Ag/0.5Cu	(1)Wetting shall be exceeded 95% coverage		
9	Resistance to Soldering Heat	Method 1: Max 260°C/10s, 3 times. Solder: Sn/3.0Ag/0.5Cu.	(1) No visible mechanical damage		
10	High Frequency Vibration	Reflow 3 times,10~2000Hz,5g,20min/Cycle,4 hours in each 3 mutually perpendicular directions (total of 12 hours) .	(2) Inductance change: Within ±10%(3) DCR: Satisfy electrical characteristic.		

Business Categories: Level 0

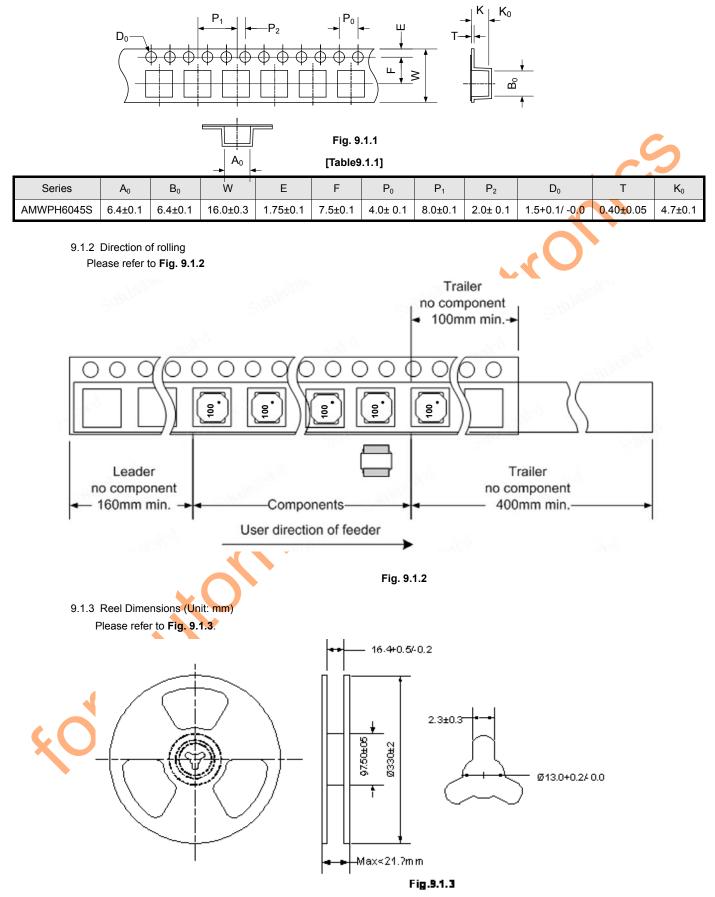
11	Mechanical Shock	Reflow 3 times, Half sine shock pulse, 100g, 6ms, 6 shocks in each 3 mutually perpendicular directions (total of 18	
12	ESD test	shocks). HBM ESD discharge waveform, 8KV, each 1 time of +/- polarity.	
13	Temperature cycling Test	Reflow 3 times, ambient temperature -40°C/(30min), ambient temperature+125°C/(30min), transforming interval:20s,1000 cycles. ① Read-outs at 500,1000cycles	
14	low temperature Storage test	Reflow 3 times, ambient temperature -40°C,1000 (+24) hours. ① Read-outs at 500h.	ics
15	High temperature Storage test	Reflow 3 times, ambient temperature +125°C,1000 hours. ① Read-outs at 500h.	 (1) No visible mechanical damage (2) Inductance change: Within ±10% (3) DCR: Satisfy electrical characteristic.
16	High Temperature And High Humidity Storage Test	(unpowered) Reflow 3 times, ambient temperature 85°C,85%RH,1000 hours. ① Read-outs at 500h.	6
17	High temperature over lifetime	Reflow 3 times, ambient temperature85±2°C,1000(+24)hours, rated current. Note: . ① Inspect the product temperature at once a week Note:Read-outs at 500h,1000h,	
18	solvent resistance test	Add Aqueous wash chemical. OKEM Clean or equivalent. Do not use banned solvents.	 No specified markings which are missing in whole or in part, faded, smeared, blurred, or shifted (dislodged) to the extent; No specimen shall have cracks, separations, crazing, swelling, softening, and degradation of body material, end caps and seals if present.





- 9.1 Tape and Reel Packaging Dimensions
 - 9.1.1Taping Dimensions (Unit: mm)

Please refer to Fig. 9.1.1 and Table 9.1.1.



- 9.1.4 Top tape strength
 - Peel-off strength: 10~150gf.

Peel-off angle: 165°~180°, refers to Fig. 9.1.4.

Peel-off speed: 300mm/min.

- 9.1.5 The number of components
 - A tape & reel package contains 1500 inductors.
- 9.1.6 The allowable number of empty chip cavities: 0 chip.

9.2 Packing Documents and Marking

- 9.2.1 Packing Documents
 - Packing documents include the following:
 - 1) Packaging list;
 - 2) Certificate of compliance (COC).
- 9.2.2 Packing QTY.
 - 4 or 6 reels in each outer case.
- 9.2.3 Marking
 - Marking label information on reels includes (see Fig. 9.2.3-1, Fig. 9.2.3-2a/2b):
 - Fig.9.2.3-2a: Shipping labels
 - a). P/O No.
 - b). Customer Part No.
 - c). Sunlord Part No.
 - d). Quantity.
 - e). Lot No.
 - f). Date code.
 - g). Inspection stamp.
 - h). MFG address as 'Made In China'.

Fig.9.2.3-2b: Production labels

- a). P/N.
- b). Quantity.
- c). Lot No.
- d). Inspect No.
- e). Inspection stamp.
- f). MFG address as 'Made In China'
- g). Sequence number.

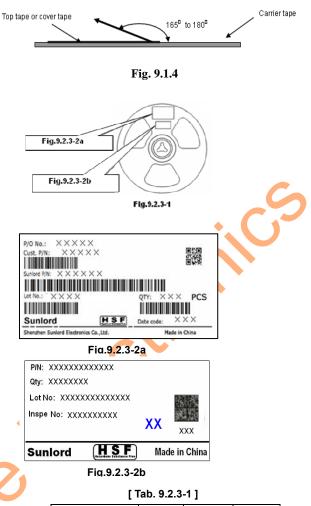
2) Marking on outer case (seeFig.9.2.3-3-4):

Out case size pleases reefers to Table 9.2.3-1.

- a). Manufacturer: Sunlord ID:
- "Shenzhen Sunlord Electronics Co., Ltd." b). Packing label include the following:

1)	BoxID.
ii)	S/PN.
iii)	P/N.
iv)	D/C.
v)	Count.

- vi) QTY.
- vii) QR code.



Packaging type	iging type L(mm)		H(mm)
TPY1	380	380	190
TPY2	380	380	250

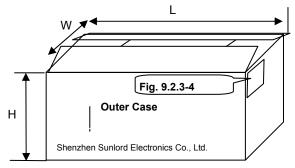


Fig. 9.2.3-3

BoxID:	B310711627000	
S/PN:	SINVCODE	
P/N:	4116620100	
D/C:	1627	
Count:	3	
QTY:	6000]

Specifications for Wire Wound SMD Power Inductor

10 Visual inspection standard of product				
File No: Effective date:		Applied to Wire Wound SMD Power Inductor Series		REV:01
No.	Defect Item	Graphic	Rejection identification	Acceptance
1	Core defect		The defect length and width (L and W) more than L/6 and W/6, NG.	AQL=0.065
2	Starvation		 Resin starved length, <i>I</i>, more than L/2, NG. IF <i>W</i> > 2mm, resin starved width, <i>w</i>, more than W/2, NG. ② IF <i>W</i>≤2mm, resin starved width, <i>w</i>, don't control. 	AQL=0.065
3	Excessive glue		The length, width or height of product beyond specified value, NG.	AQL=0.065
4	Cold solder		Cold solders / more than1mm, NG.	AQL=0.065
5	Solder icicle		The height H of product beyond specified value, NG;	AQL=0.065
6	Marking defect		 The content of marking 1) is indistinct, 2) disagrees with current product P/N requirements, NG; Intersection angle by L1 and L2 more than 45°, NG. 	AQL=0.065

Sunlord Specifications for Wire Wound SMD Power Inductor

Recommended Soldering Technologies 11.1Re-flowing Profile:

- \triangle Preheat condition: 150 ~200°C/60~180sec.
- \triangle Allowed time above 217°C: 60~150sec.
- \triangle Allowed time above 255 °C: 30sec. ref.
- △ Max temp: 260°C
- \triangle Max time at max temp: 5sec.
- △ Solder paste: Sn/3.0Ag/0.5Cu
- △ Allowed Reflow time: 3x max
 - Please refer to Fig. 11.1-1.

[Note: The reflow profile in the above table is only for qualification and is not meant to specify board assembly profiles. Actual board assembly profiles must be based on the customer's specific board design, solder paste and process, and should not exceed the parameters as the Reflow profile shows.]

11.2 Iron Soldering Profile:

- \triangle Iron soldering power: Max. 300W
- \triangle Pre-heating: 150°C/60sec.
- △ Soldering Tip temperature: 390°C ~410°C
- \triangle Soldering time: 3sec. Max.
- △ Solder paste: Sn/3.0Ag/0.5Cu
- $\label{eq:max_state} \begin{array}{ll} \bigtriangleup & \mbox{Max.1 times for iron soldering} \\ \mbox{Please refer to $Fig. 11.2-1}. \end{array}$

[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]

12 Precautions

- 12.1 Surface mounting
 - Mounting and soldering condition should be checked beforehand.
 - Applicable soldering process to this product is reflow soldering only.
 - Recommended conditions for repair by soldering iron:
 - Preheat the circuit board with product to repair at 150 °C for about 1 minute.
 - Put soldering iron on the land-pattern.
 - Soldering iron's temperature: 350 °C maximum/Duration: 3 seconds maximum/1 time for each terminal.
 - The soldering iron should not directly touch the inductor.

Product once removes from the circuit board may not be used again.

12.2 Handing

- Keep the products away from all magnets and magnetic objects.
- Be careful not to subject the products to excessive mechanical shocks.
- Please avoid applying impact to the products after mounted on pc board.
- Avoid ultrasonic cleaning.

12.3 Storage

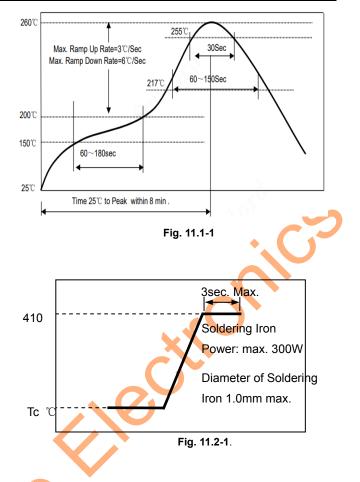
- To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled.
- Recommended conditions: -10°C~40°C, 70%RH (Max.)
- Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, product should be used with one year from the time of delivery.
 - In case of storage over 6 months, solderability shall be checked before actual usage.

12.4 Regarding Regulations

- Any Class- I or Class- II ozone-depleting substance (ODS) listed in the Clean Air Act in US for regulation is not included in the products or applied to the products at any stage of whose manufacturing processes.
- Certain brominated flame retardants (PBBs,PBDEs) are not used at all.
- The products of this specification are not subject to the Export Trade Control Order in China or the Export Administration Regulations in US.

12.5 Guarantee

- The guaranteed operating conditions of the products are in accordance with the conditions specified in this specification.
- Please note that Sunlord takes no responsibility for any failure and/or abnormality which is caused by use under other than the aforesaid operating conditions.
- 12.6 Please make sure to record the lot number on the label when using Sunlord's products in order for good traceability.



Business Categories: Level 0